

## 4.2 Board Layout

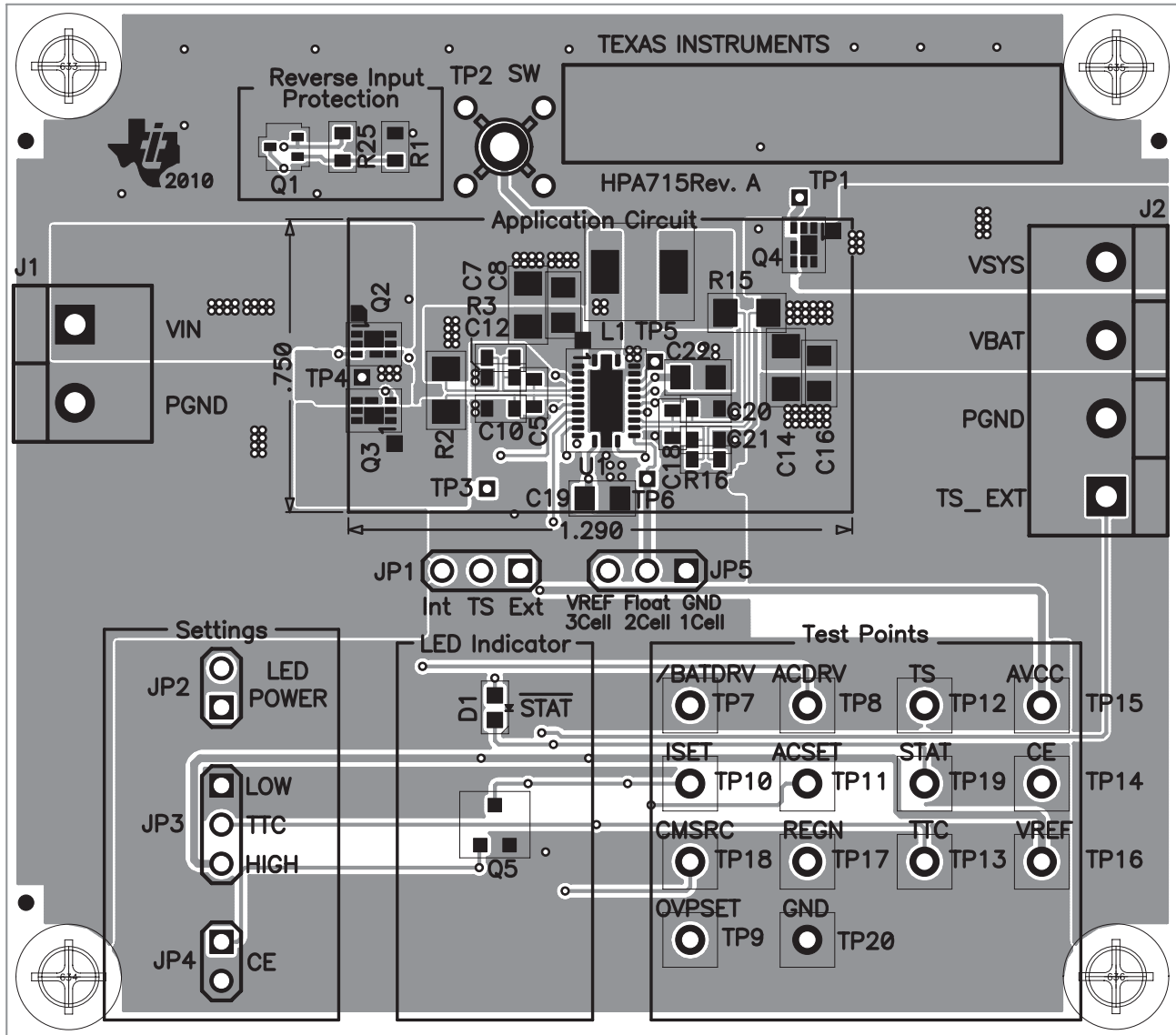


Figure 2. Top Assembly

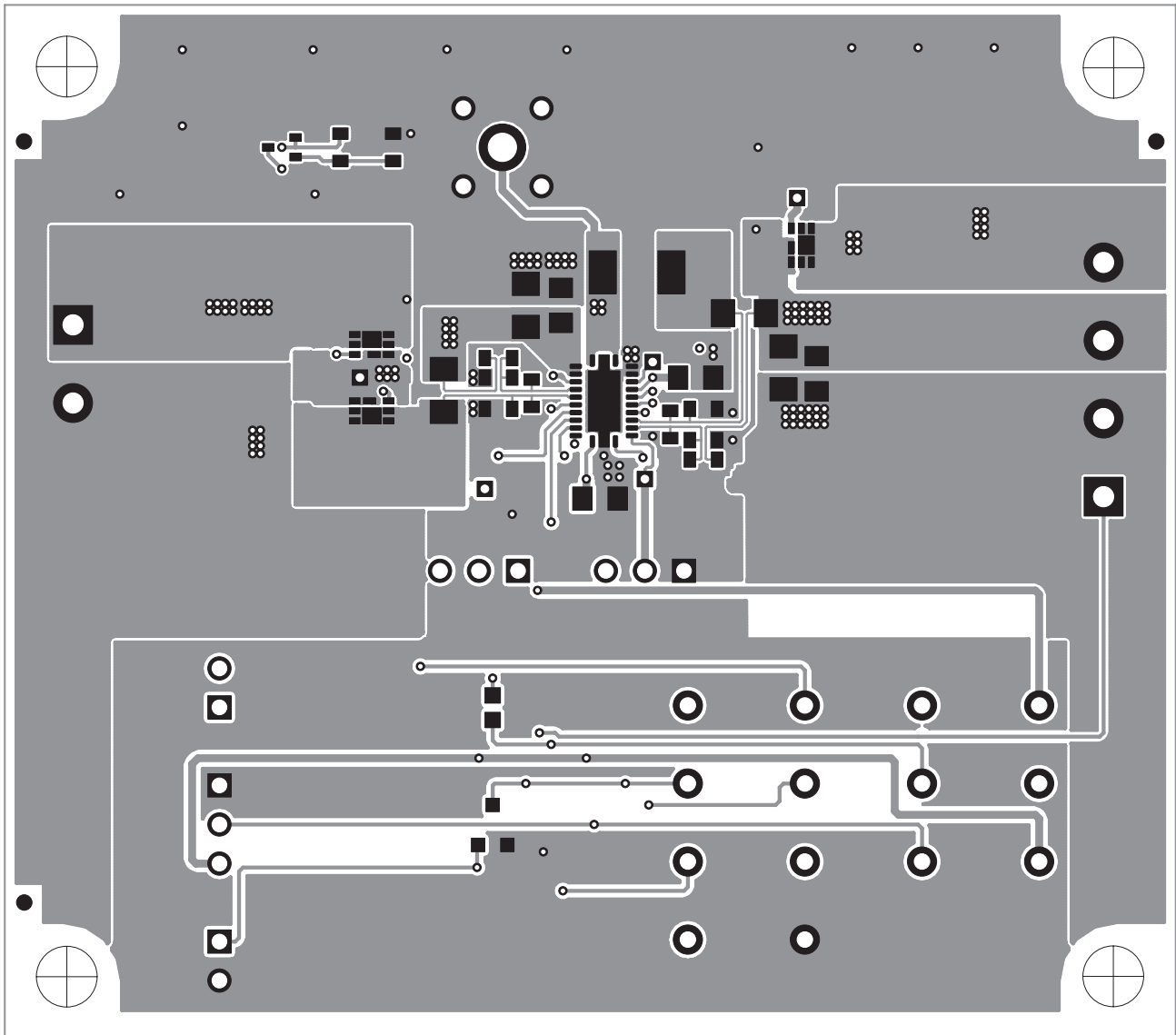


Figure 3. Top Layer

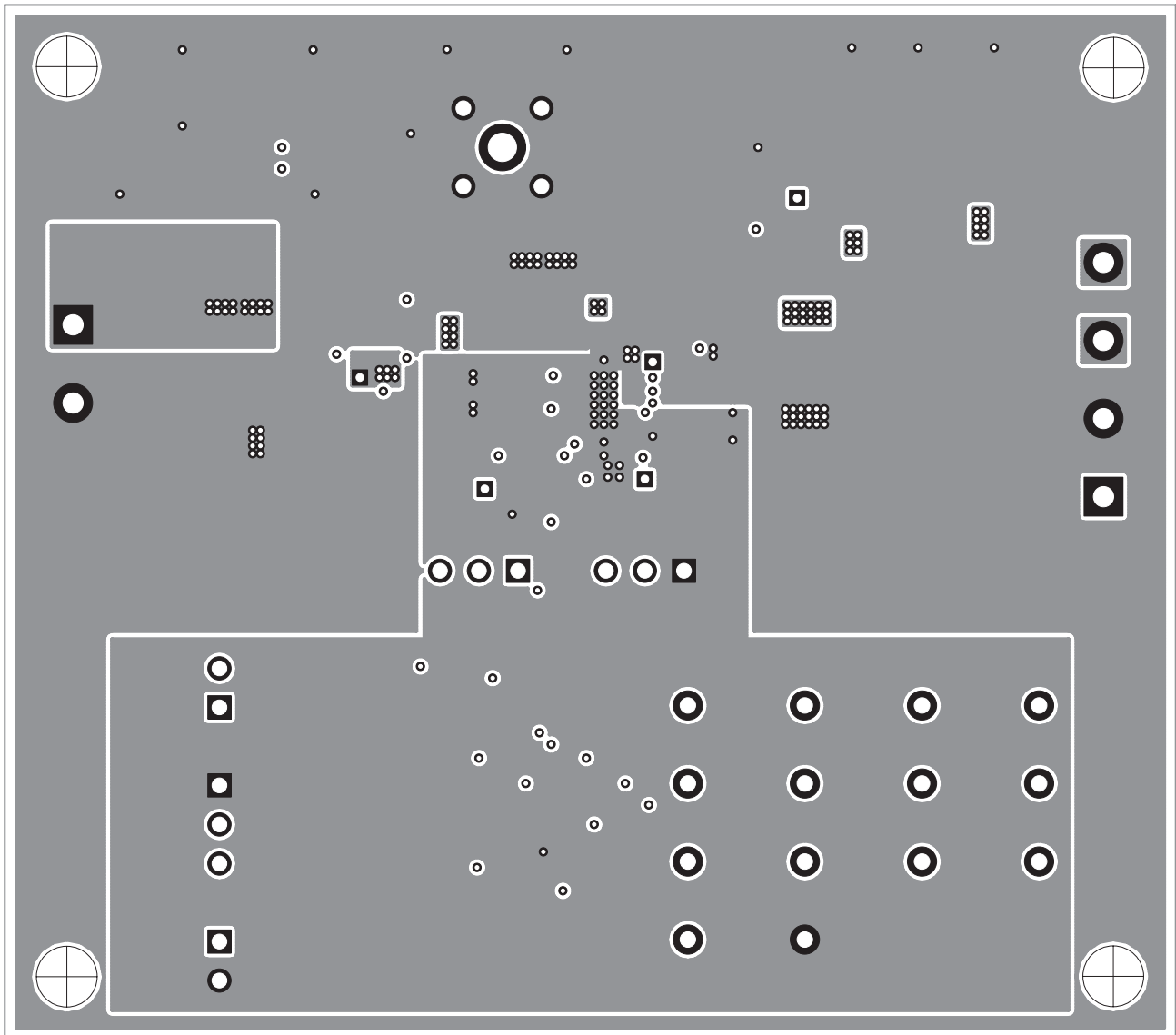


Figure 4. Second Layer

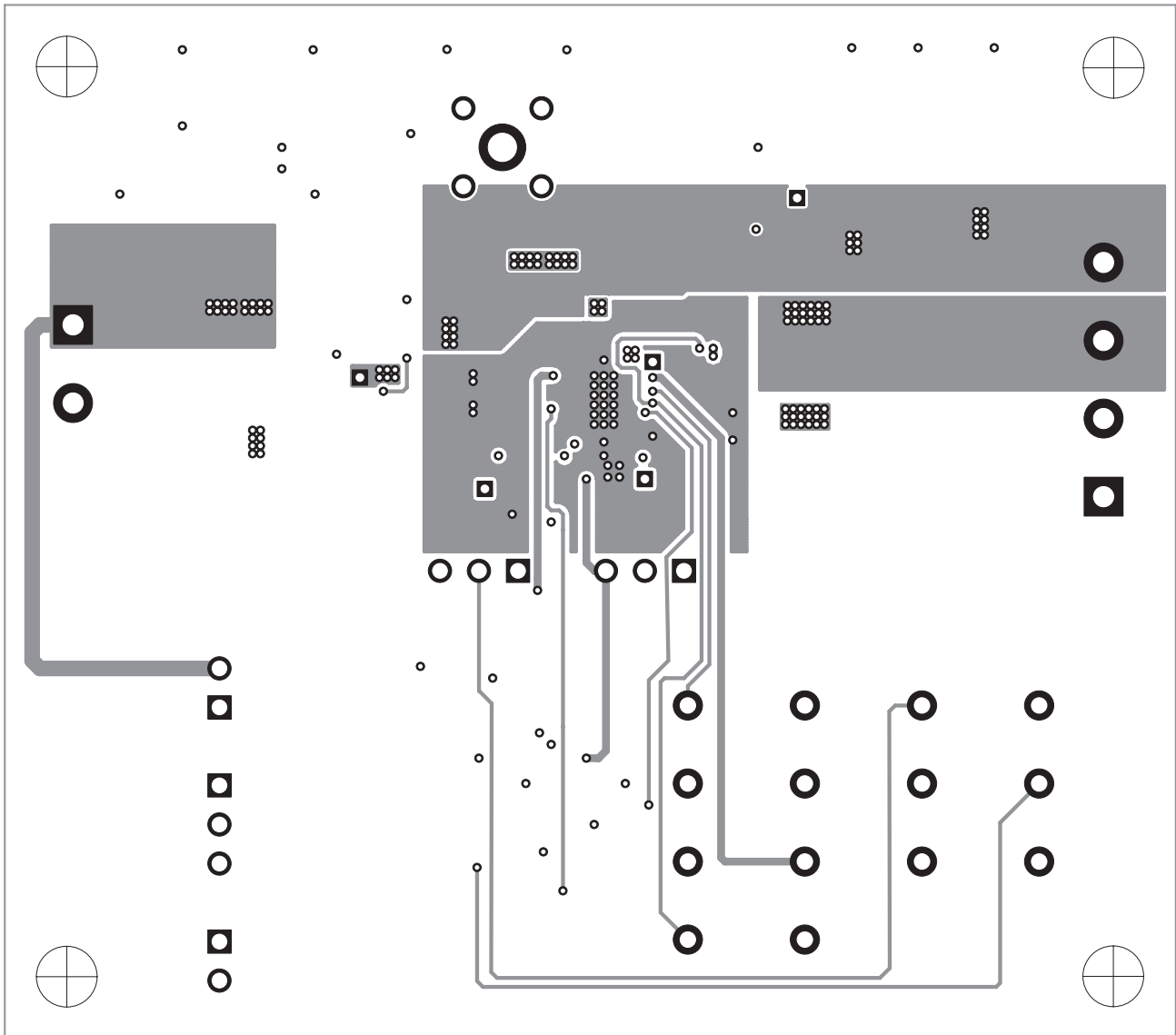
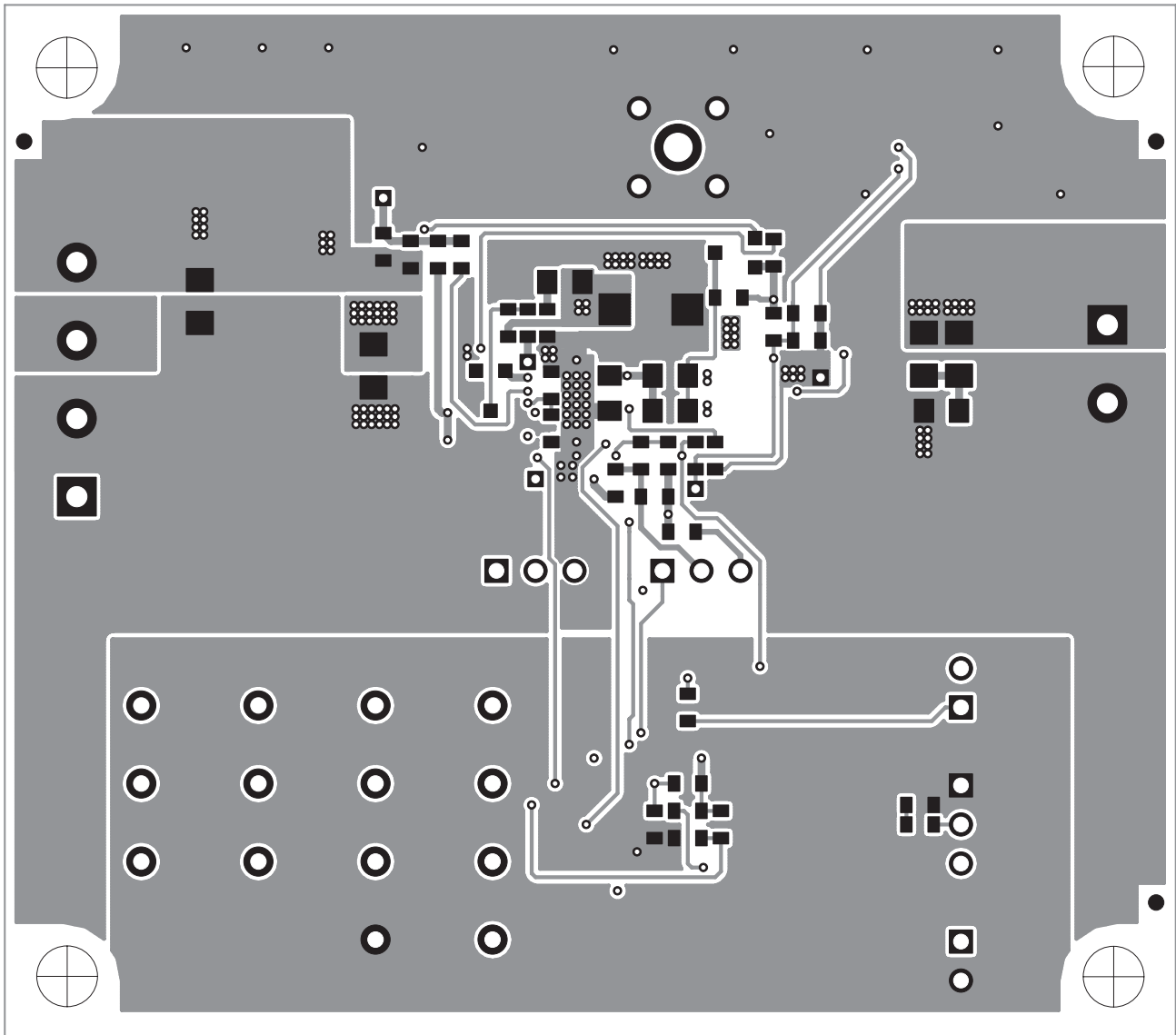


Figure 5. Third Layer



**Figure 6. Bottom Layer**

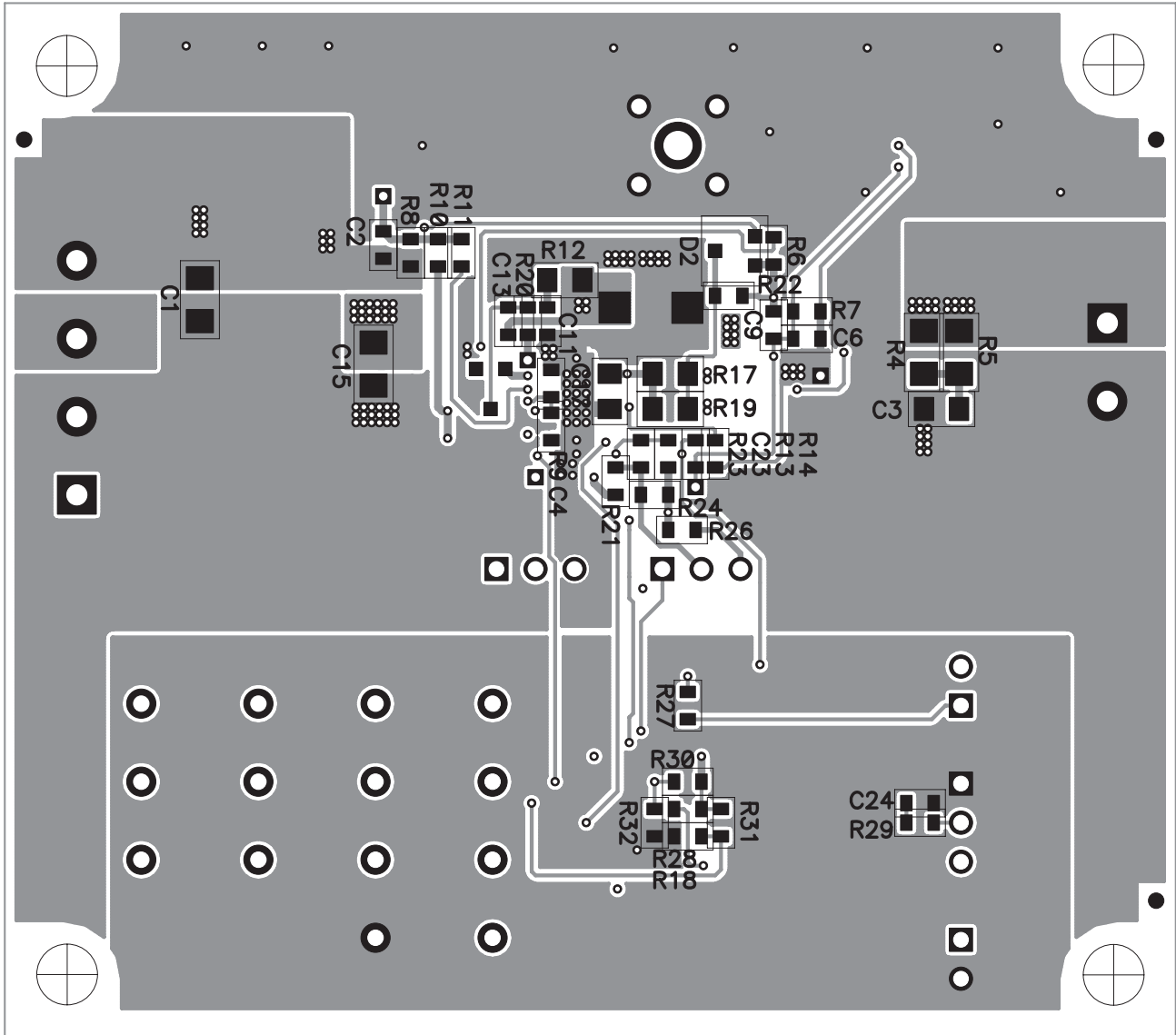


Figure 7. Bottom Assembly

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